



Instructor Introduction

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My Technical Background

- Wonsun Ahn
 - First name is pronounced one-sun (if you can manage)
 - Or you can just call me Dr. Ahn (rhymes with naan)
- PhD in CPU Design and Compilers
 - University of Illinois at Urbana Champaign
- Industry Experience
 - Software engineer, field engineer, technical lead, manager
 - Bluebird Corporation (70-person startup company)
 - ☐ Manufactures industrial hand-held devices from top to bottom
 - □ Me: Built software stack based on Windows Embedded
 - IBM Research (thousands of people)
 - □ Does next-gen stuff like carbon nanotubes, quantum computers
 - □ Me: Designed supercomputers for ease of parallel programming

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My World View

- Everything is connected
 - Pandemic: If my neighbors catch the virus, so will I
 - Environment: If my neighbors pollute, I will feel the effects
 - Economy: Think of how the subprime mortgage crisis spread
- Zero-sum thinking (old way of thinking)
 - "If you get a larger slice of the pie, I get a smaller slice."
 - Therefore, if you lose, I win (and vice versa)
- Zero-sum thinking no longer works
 - If you catch the virus, do I become safer from the virus?
- Collaboration is replacing competition

Collaboration is Replacing Competition

- Is happening in all spheres of life
- Collaboration is also happening in the IT industry
 - The open source movement
 - Increasing importance of the software/hardware ecosystem
 - Increasing importance of the developer community
- Collaboration is also important for learning
 - During my undergrad years, what do I remember best?
 - Stuff that I explained to my classmates
 - Stuff that my classmates taught me



Supporting Collaborative Learning

- I never grade on a curve
 - You will not be competing against your classmates
 - You are graded on your own work on an absolute scale
- You will be a member of a Team
 - You are already a member of the class on Microsoft Teams
 - I encourage you to be on Teams at most times (I will too)
 - ☐ You can install app on both laptop and cell phone
 - If you have a question, you can ask in the Team "Posts" tab
 - ☐ Either your classmate or your instructor will answer
 - You can chat with any individual on the Team
 - ☐ "Manage Team" item in the "..." Team context menu



Supporting Collaborative Learning

- You will be a member of a Group
 - On Teams, you are part of a chat group of 7~8 members
 - Members are a good mix of in-person and online students
 - Your instructor is also a member of each Group
 - It is a smaller support group where you can talk more freely
- You are allowed to discuss TopHat lecture questions
 - The goal is no-student-left-behind (pun intended)
 - Discuss answers on Teams even before submitting them
 - Form a basis of knowledge for doing homeworks and exams



Course Introduction

Structure of the Course

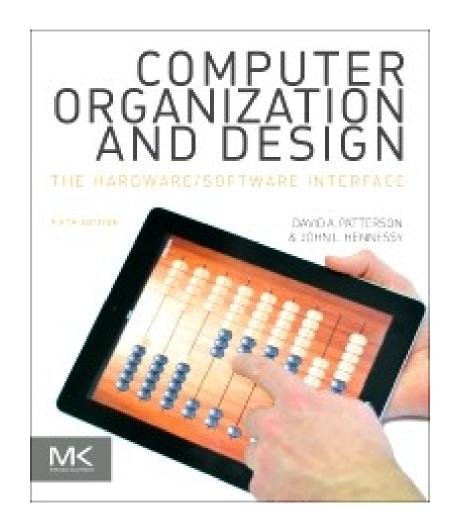


- (45% of grade) Three midterms
- (20% of grade) Two projects
 - Implementing a CPU simulator using C programming language
- (20% of grade) Four homeworks
- (15% of grade) Participation
 - TopHat lecture questions, Teams participation
- Class resources:
 - Canvas: announcements, Zoom meetings, recorded lectures
 - GitHub: syllabus, lectures, homeworks, projects
 - Tophat: online lecture questions
 - GradeScope: homework / projects submission, grading and feedback
 - Microsoft Teams: Online / off-line communication



Textbook (You Probably Have it)

"Computer Organization and Design - The Hardware/Software Interface" by David Patterson and John Hennessy Fifth Edition - Morgan & Kaufmann.



For More Details



- Please refer to the course info page: https://github.com/wonsunahn/CS1541_Fall2020/bl ob/master/course-info.md
- Please follow the course schedule syllabus: https://github.com/wonsunahn/CS1541_Fall2020/blob/master/syllabus.md

TODO



Submit the TopHat survey questions (due 8/21)

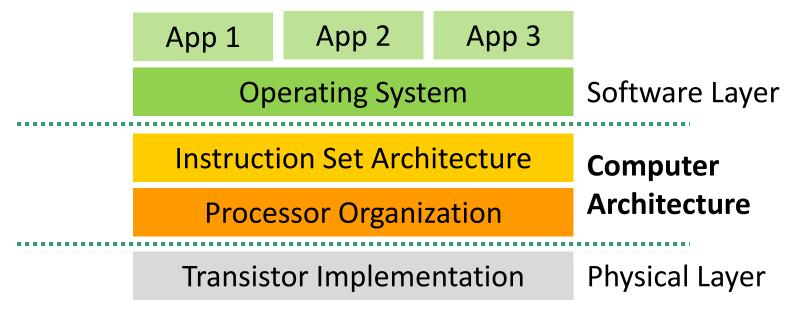
What is Computer Architecture?



- At a high-level: how a computer is built
 - Computer here meaning the processor (CPU)
- You probably heard of a similar term before: ISA
 - ISA (Instruction Set Architecture)
- Review: what is defined by an ISA?
 - Set of instructions usable by the computer
 - Set of registers available in the computer
 - Functional attributes are clearly defined (it's the interface)
- What is not defined by an ISA?
 - Speed of computer
 - Energy efficiency of computer
 - Reliability of computer
 - Performance attributes are undefined (intentionally so)



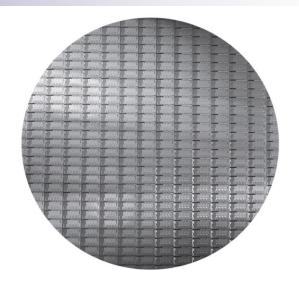
Computer Architecture Defined



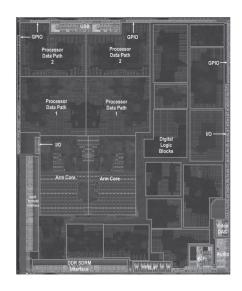
- Computer Architecture = ISA + Processor Organization
 - Processor organization is also called Microarchitecture
- Performance is decided by:
 - Processor organization (internal design of the processor)
 - Transistor implementation (semiconductor technology)

Scope of Class

Physical layer is beyond the scope of the class



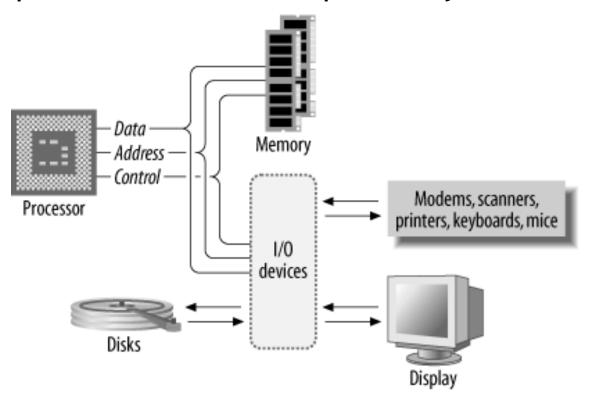
- We will focus mostly on processor organization
 - And how performance goals are achieved



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Scope of Class

Computer architecture is part of system architecture

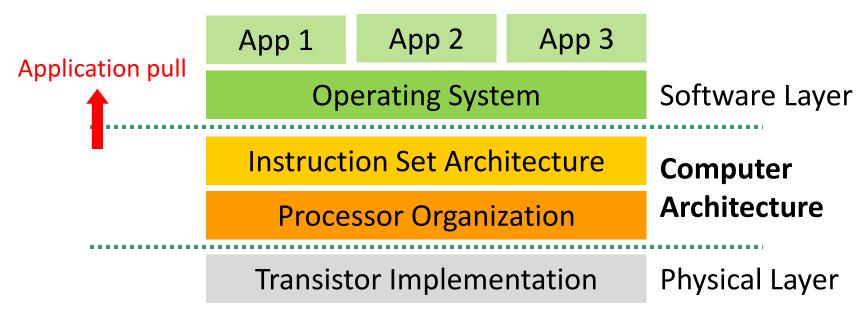


Other components beside processor is beyond the scope

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Application Pull

Different applications pull in different directions



- Real-time app (e.g. Game): Short latency
- Server app: High throughput
- Mobile app: High energy-efficiency (battery life)
- Mission critical app: High reliability
- An app typically has multiple goals that are important

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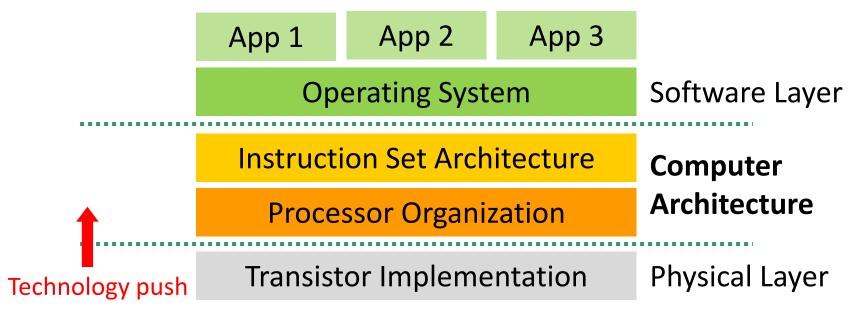
Application Pull

- Some goals can be incompatible
 - E.g. Speed and energy-efficiency are incompatible
 - ☐ Running is faster than walking but uses more energy
 - ☐ A Ferrari is faster than a Prius but has worse fuel efficiency
 - E.g. Reliability is incompatible with many other goals
 - ☐ If you use redundancy, you use twice the amount of energy
- Even when sharing a goal, apps have unique needs
 - Scientific apps need lots of floating point units to go fast
 - Database apps need lots of memory cache to go fast
- An architecture is a compromise among all the apps
 - When app achieves market critical mass, designs diverge (Mobile chips / Server chips / GPUs / TPUs diverged)
 - Sometimes even ISAs diverge (GPUs and TPUs)



Technology Push

Trends in technology pushes architecture too



- Trends can be advances in technology
- Trends can be constraints technology couldn't overcome
- * "Technology" in CPU design refers to the physical layer
 - Manufacturing technology used for transistor implementation

Technology Advances

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Advances in Technology

- Technology has been advancing at lightning speed
- Architecture and IT as a whole were beneficiaries
- Technology advance is summarized by Moore's Law
 - You probably heard of it at some point. Something about ...
 - "X doubles every 18-24 months at constant cost"
- Is X:
 - CPU performance?
 - CPU clock frequency?
 - Transistors per CPU chip?
 - Area of CPU chip?

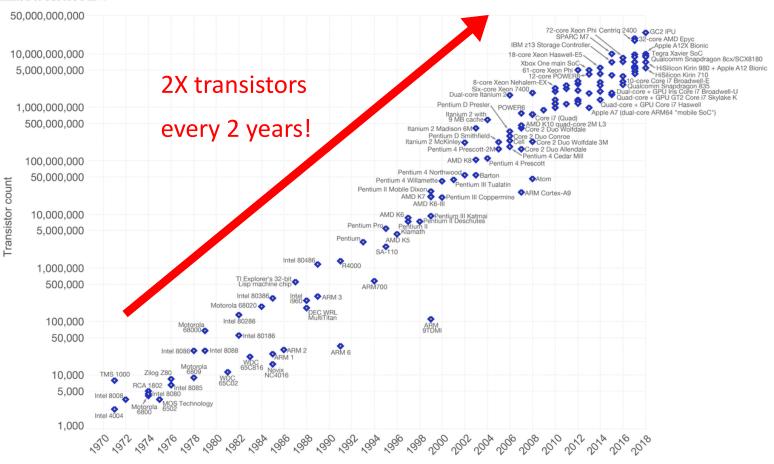




Moore's Law – The number of transistors on integrated circuit chips (1971-2018)

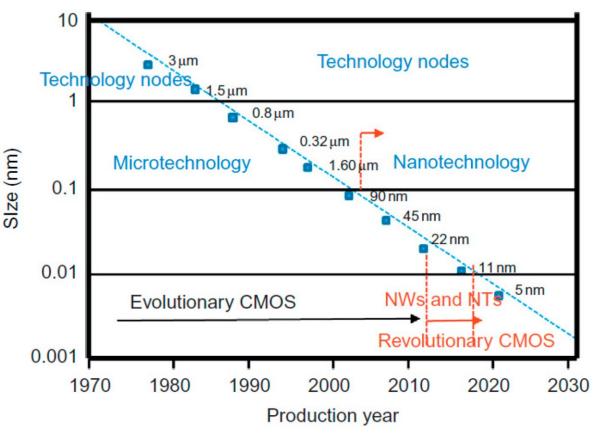


Moore's law describes the empirical regularity that the number of transistors on integrated circuits doubles approximately every two years. This advancement is important as other aspects of technological progress – such as processing speed or the price of electronic products – are linked to Moore's law.



Miniaturization of Transistors





Data source: Radamson, H.H.; He, X.; Zhang, Q.; Liu, J.; Cui, H.; Xiang, J.; Kong, Z.; Xiong, W.; Li, J.; Gao, J.; Yang, H.; Gu, S.; Zhao, X.; Du, Y.; Yu, J.; Wang, G. Miniaturization of CMOS. *Micromachines* **2019**, *10*, 293.

- Moore's Law has been driven by transistor miniaturization
 - CPU chip area hasn't changed much

Future of Moore's Law



- The semiconductor industry has produced roadmaps
 - Semiconductor Industry Association (SIA): 1977~1997
 - International Technology Roadmap for Semiconductors (ITRS): 1998~2016
 - International Roadmap for Devices and Systems (IRDS): 2017~Present
- IRDS Lithography Projection (2020)

Year of Production	2018	2020	2022	2025	2028	2031	2034
Technology Node (nm)	7	5	3	2.1	1.5	1.0	0.7

- Looks like Moore's Law will continue into foreseeable future
- IRDS does not project significant increase in CPU chip size
- Increases in transistors will come from transistor density

IRDS isn't Perfect



ITRS (predecessor of IRDS) has made corrections before



- After all, you are trying to predict the future
- But architects rely on the roadmap to design future processors

Moore's Law and Performance



- Million-dollar question: Did Moore's Law result in higher performance CPUs?
- Please go to your respective Teams chat groups
 - But stay in the Zoom room and use only chat on Teams
 - To have chat content accessible to asynchronous students
- 1. Get to know each other
- 2. And then try to answer the following questions:
 - What do you think? Are CPUs getting faster?
 - If not, why do you think so? If yes, again why do you think so?
- 3. After 10 minutes, we will share discussions with class

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Are CPUs getting Faster?

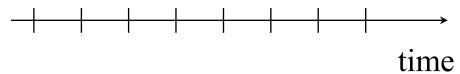
- Yes!
- Clock speeds are increasing, power draw is decreasing -Andrew
- More cores Jason
- Visual Studio compilation is actually faster -Nick

- No!
- Clock speeds are plateauing recently
 - Jason
- Seems stagnant from user's perspective e.g. Visual Studio - Josh

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Components of Execution Time

Processor activity happens on clock "ticks" or cycles



On each tick, bits flow through logic gates and are latched

Execution time =
$$\frac{\text{seconds}}{\text{program}}$$

$$\frac{\text{seconds}}{\text{program}} = \frac{\text{cycles}}{\text{program}} \quad X \quad \frac{\text{seconds}}{\text{cycle}}$$

$$= \frac{\text{instructions}}{\text{program}} \quad X \quad \frac{\text{cycles}}{\text{instructions}} \quad X \quad \frac{\text{seconds}}{\text{cycle}}$$

Improving Execution Time

$$\frac{\text{instructions}}{\text{program}}$$
 X $\frac{\text{cycles}}{\text{instructions}}$ X $\frac{\text{seconds}}{\text{cycle}}$

- - Also known as CPI (Cycles Per Instruction)
 - IPC (Instructions Per Cycle) = $\frac{\text{instructions}}{\text{cycles}}$ = reverse of $\frac{\text{cycles}}{\text{instructions}}$ Higher IPC leads to shorter execution time
- Improving instructions program:
 - Less instructions leads to shorter execution time
 - ISAs that do a lot of work with one instruction shortens time

Moore's Law and Performance

- Million-dollar question: Did Moore's Law result in higher performance CPUs?
- Law impacts both architecture and physical layers

Instruction Set Architecture

Computer

Processor Organization

Architecture

Transistor Implementation

Physical Layer

- Processor Organization: many more transistors to use in design
- Transistor Implementation: smaller, more efficient transistors

Moore's Law Impact on Architecture

- So where did architects use all those transistors?
- Well, we will learn this throughout the semester ©
 - Pipelining
 - Parallel execution
 - Prediction of values
 - Speculative execution
 - Memory caching
 - In short, they were used to improve frequency or IPC
- Let's go on to impact on the physical layer for now

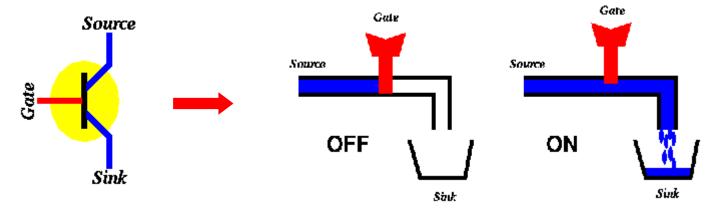
Moore's Law Impact on Physical Layer

- CPU frequency is also impacted by transistor speed
 - As well as how many transistors are in between clock ticks (which is determined by processor organization)
- So did Moore's Law result in faster transistors?
 - In other words, are smaller transistors faster?

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Speed of Transistors

Transistor 101: Transistors are like faucets!

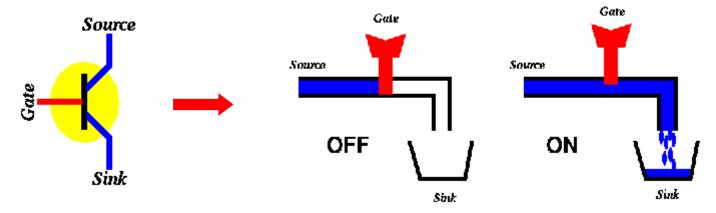


- To make a transistor go fast, do one of the following:
 - Reduce distance from source to sink (channel length)
 - Reduce bucket size (capacitance) ↓
 - Increase water pressure (supply voltage) 企

Smaller Transistors are Faster!



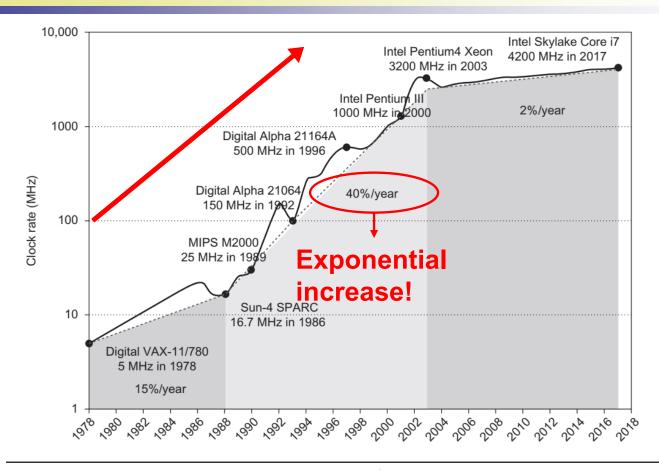
Transistor 101: Transistors are like faucets!



- When a transistor gets smaller:
 - Channel length (channel resistance) is reduced ↓
 - Capacitance is reduced ↓
- So, given the same supply voltage, smaller is faster!
- So, did Moore's Law enjoy faster and faster frequencies?

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Yes, for a while ...

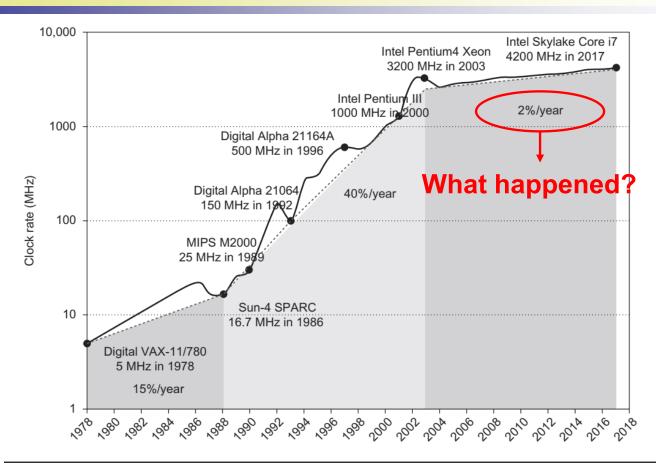


Source: Computer Architecture, A Quantitative Approach (6th ed.) by John Hennessy and David Patterson, 2017

- Improvements in large part due to transistors
 - Processor design also contributed but we'll discuss later

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But not so much lately



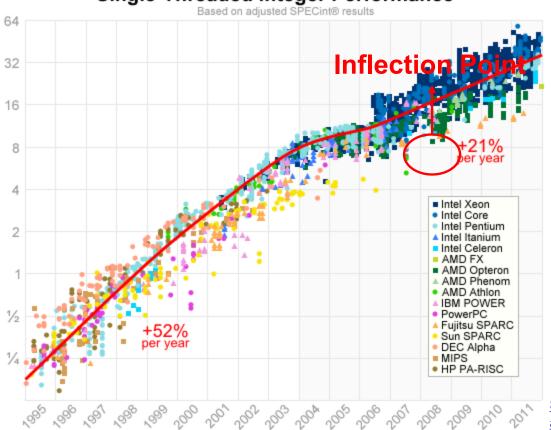
Source: Computer Architecture, A Quantitative Approach (6th ed.) by John Hennessy and David Patterson, 2017

Suddenly around 2003, frequency scaling stops

Dent in CPU Performance



Single-Threaded Integer Performance



Source: https://preshing.com/20120208/ a-look-back-at-single-threaded-cpu-performance/

- This caused a big dent in CPU performance at 2003
- Improvements henceforth only came from architecture
 - From improvements to IPC (instructions per cycle)

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So What Happened? TDP.

- TDP (Thermal Design Power):
 - Maximum heat (power) that cooling system can handle
 - Cooling system hasn't improved much over generations (Typically a CPU cooling fan attached with thermal paste)
- CPU Power = A * N * CFV² must be < TDP</p>
 - A = Activity factor (% of transistors with activity)
 - N = Number of transistors

 - F = Frequency
 - V = Supply Voltage



What happens to each factor with Moore's Law?

TDP and Moore's Law



- CPU Power = A * N * CFV² with Moore's Law
 - A = Activity factor
 - N = Number of transistors ① ①

 - F = CPU frequency ①
 - V = CPU Supply Voltage
- Reductions in C cannot offset increases in N and F
 - Q) How did CPU frequency keep increasing up to 2003?
 - A) By maintaining power through reductions in Voltage \P
 - Q) Wait! Voltage reduction reduces frequency! (Transistor 101)
 - A) Alright, time to do MOSFET 101

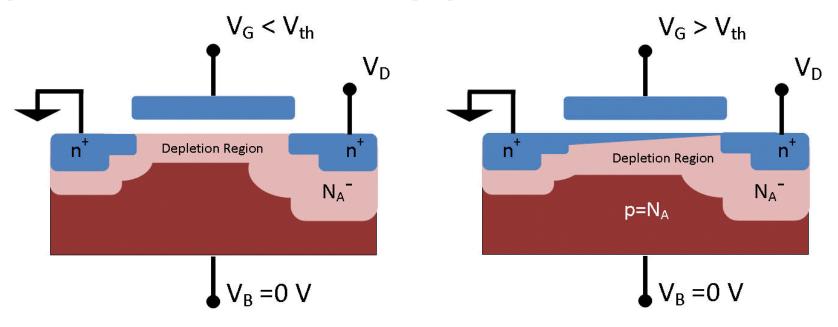
MOSFET 101

Source



MOSFET (Metal Oxide Silicon Field Effect Transistor)

[A MOSFET transistor switched off] [A MOSFET transistor switched on]

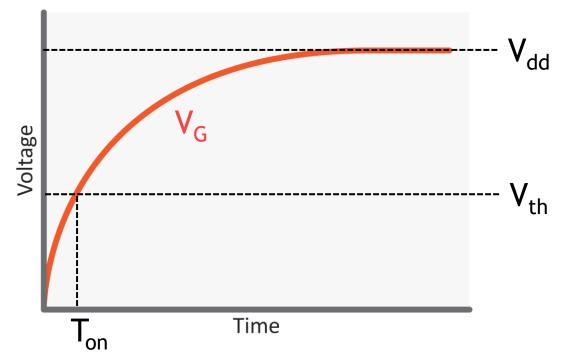


- Gate is switched on when V_G reaches a threshold V_{th}
 - By creating a channel in depletion region through field effect
 - V_{th}: threshold voltage (minimum voltage to create channel)

MOSFET 101



RC charging curve of V_G

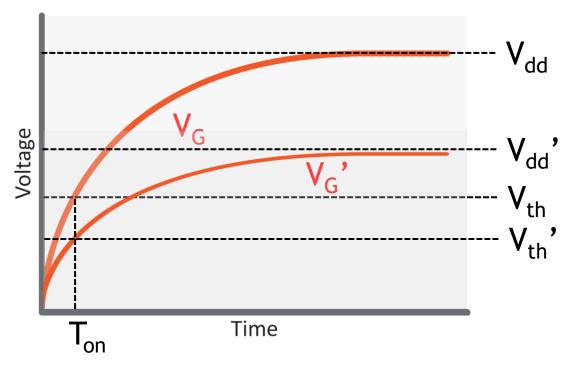


- \blacksquare Speed (T_{on}) is determined by V_{dd} if V_{th} is fixed
 - V_{dd} is the CPU supply voltage (the water pressure)
 - If V_{dd} is lower, V_G will reach V_{th} more slowly (low pressure)

MOSFET 101



RC Charging Curve of V_G



■ Speed (T_{on}) is maintained while reducing V_{dd} to V_{dd} , if V_{th} is also reduced to V_{th} .

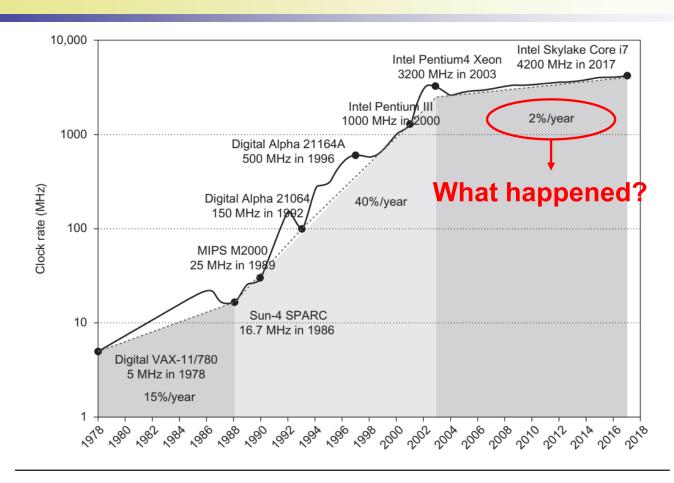
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Dennard Scaling

- So in the end, this is what happens ...
- CPU Power = A * N * CFV² with Moore's Law
 - A = Activity factor
 - N = Number of transistors 企 企

 - F = CPU frequency 企
- Factors balance each other out to make power constant
- This recipe for scaling frequency while keeping power constant is called Dennard Scaling

End of Dennard Scaling

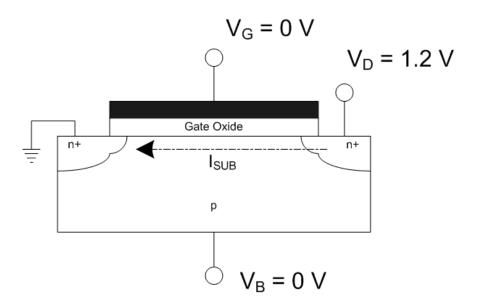


And around 2003 is when Dennard Scaling ended

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Limits to Dropping V_{th}

- Subthreshold leakage
 - Transistor leaks current even when gate is off $(V_G = 0)$

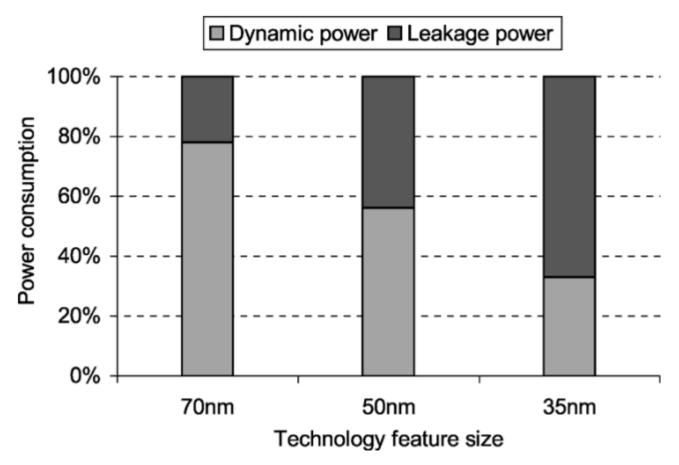


- This leakage current translates to leakage power
- Leakage worsens when V_{th} is dropped (related to oxide thickness)



Leakage Power across Generations

Leakage power has increased across technology nodes



Source: L. Yan, Jiong Luo and N. K. Jha, "Joint dynamic voltage scaling and adaptive body biasing for heterogeneous distributed real-time embedded systems," in *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems*, vol. 24, no. 7, pp. 1030-1041, July 2005

End of Dennard Scaling



- Power_{CPU} = Power_{dynamic} + Power_{leakage}
 - Power_{dynamic} = A * N * CFV²
 - Power_{leakage} = $f(N, V, V_{th}) = N * V * e^{-Vth}$
 - Leakage worsens exponentially when V_{th} is dropped
 - Catch-22: when dropping V_{th} , Power_{dynamic} ψ but Power_{leakage} ψ
 - That means V_{th} can't be reduced and V can't be reduced
- CPU Power = A * N * CFV² + N * V * e^{-Vth}
 - A = Activity factor
 - N = Number of transistors ① ①

 - F = CPU frequency ⇔ (Can't increase without violating TDP)
 - $V = CPU Supply Voltage \Leftrightarrow (Due to fixed V_{th})$
 - V_{th} = CPU Threshold Voltage \Leftrightarrow (Due to leakage power)

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Free Ride is Over

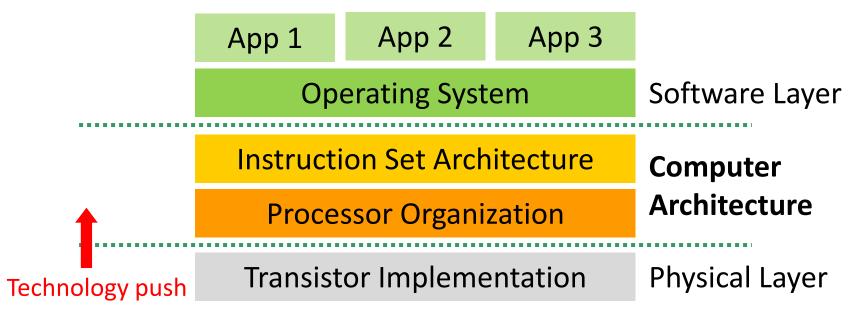
- "Free" speed improvements from transistors is over
- Now it's up to architects to improve performance
 - Remember Moore's Law is still alive and well
 - Architects are flooded with extra transistors each generation
- Now is a good time to discuss technology constraints
 - Since we already mentioned a big one: TDP

Technology Constraints

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Technology Constraints

Constraints in technology push architecture too



- Power Wall: Thermal Design Power (TDP) constraint
- Memory Wall: Constraint in bandwidth to memory
- Variability: Limits in the precision of manufacturing technology
- Processor must be designed to meet all constraints

Power Wall



- Power_{CPU} = Power_{dynamic} + Power_{leakage} = $A * N * CFV^2 + N * V * e^{-Vth}$
 - Leakage power is also called static power
 - This total CPU power cannot exceed TDP
- Moore's Law transistor scaling means two things:
 - N = Number of transistors 企 企

 - Reductions in C does not compensate for increases in N
- Architects must use tricks to keep power in check
 - To keep packing more transistors to increase performance

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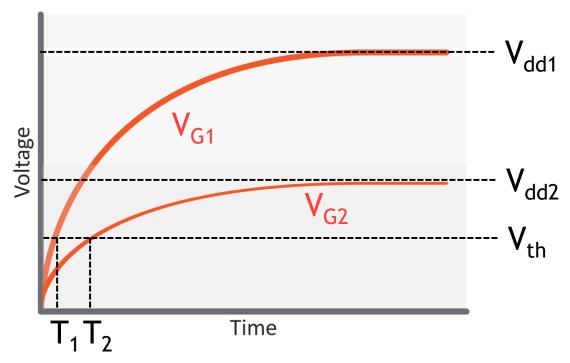
1. Reducing Dynamic Power

- CPU Power = A * N * CFV² + N * V * e^{-Vth}
- Reducing A (Activity): Clock gating
 - Disables the clock signal to unused parts of the chip (idle cores)
 - Wake-up is instantaneous (the moment clock signal goes in)
- Reducing F (Frequency) and V (Voltage)
 - When F is reduced, V can also be reduced (Transistor 101 and water pressure, remember?)
 - Dynamic Voltage Frequency Scaling (DVFS) done on multi-cores
 - ☐ Slow down low-priority cores, speed up high-priority cores

DVFS and Clock Speed



RC Charging Curve of V_G



- $ightharpoonup V_{dd1}
 ightharpoonup V_{dd2}$ saves power, but slows $T_1
 ightharpoonup T_2$
- $ightharpoonup V_{dd2}
 ightarrow V_{dd1}$ uses more power, but speeds up $T_2
 ightarrow T_1$

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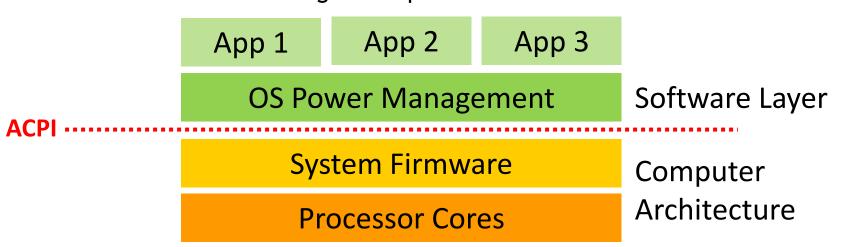
2. Reducing Leakage Power

- CPU Power = A * N * CFV² + N * V * e^{-Vth}
- Reducing N (Transistor Number): Power gating
 - Disables power to unused parts of the chip (unused cores)
 - Eliminates dynamic power and leakage power to those parts
 - Drawback: wake-up takes a much longer time than clock gating
 - ☐ Delay for supply voltage to stabilize
 - ☐ Delay to backup and restore CPU state to/from memory
- Reducing V (Voltage): DVFS also helps here

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OS Manages Power

- Who decides which cores to clock gate and power gate?
- Who decides how to apply DVFS to the cores?
- ACPI (Advanced Configuration and Power Interface)
 - OS performs power management using this interface
 - □ OS knows best which threads to prioritize for best user experience
 - Open standard interface to system firmware
 - ☐ Firmware sends signals to processor cores to control them





3. Simpler Processor Design

- Plenty of transistors but not enough power
 - Power becomes the ultimate currency in processor design
- To eke out the last bit of performance out of a thread
 - Architects must use increasingly complex logic (more power)
 - Diminishing returns on performance for power investment
- Push towards simpler architectures:
 - Multi-cores: Run multiple programs (threads) on simple cores
 - GPUs: Run each instruction on massively parallel compute units
 - Caches: Memory caches are power efficient (low dynamic power)

Memory Wall

- Refers to both latency (ns) and bandwidth (GB/s)
 - CPU cycle time and overall performance increased dramatically
 - Memory (DRAM) latency and bandwidth have lagged far behind

■ Why?

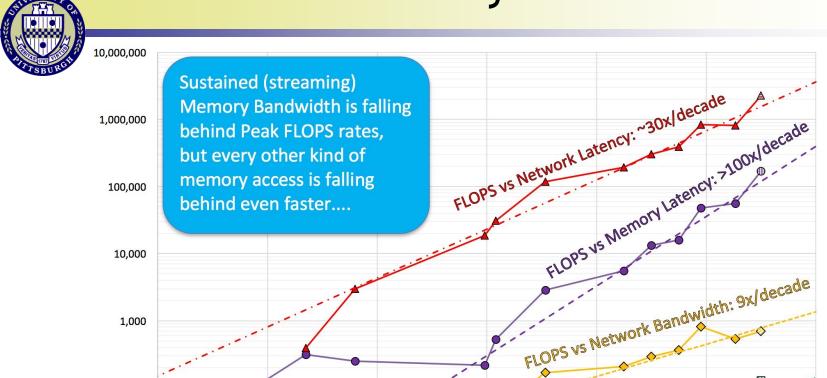
Limit on the number of CPU / DRAM pins that can be soldered on





- DRAM manufacturers have traditionally prioritized capacity
- DDR1 (1998): 1.6 GB/s → DDR4 (2014): 25.6 GB/s (Impressive? Not so much compared to CPU performance)

Memory Wall



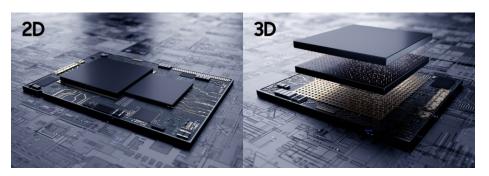
Source: SC16 Invited Talk ""Memory Bandwidth and System Balance in HPC Systems" by John D. McCalpin

FLOPS vs Memory Bandwidth: 4.5x/decade

FLOPS = floating point operations per second (performance)

Memory Wall

- Where did the Memory Wall push architecture?
- Caches: If hit in cache, no need to go to memory
 - Caching reduces both data access latency/bandwidth
- 3D-Stacked Memory: Stack CPU on top of memory
 - Drill vias, or holes, through silicon to bond CPU with memory
 - Through silicon vias (TSVs) have low latency / high bandwidth



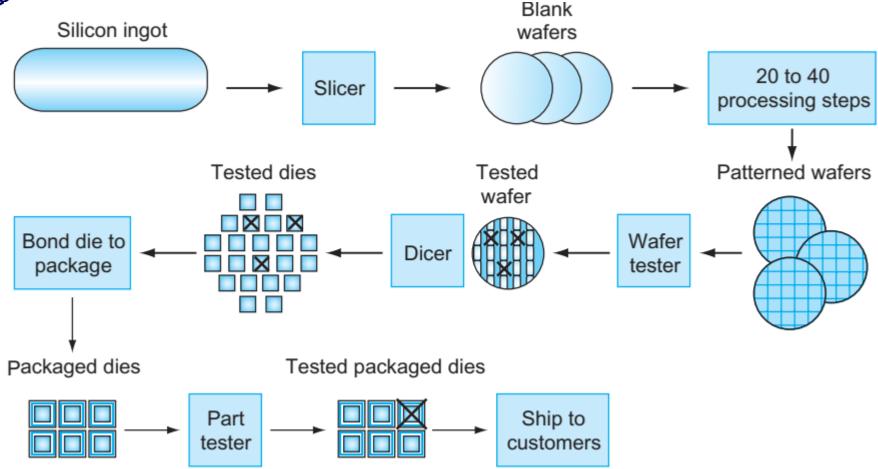
THE THE PERSON NAMED IN COLUMN 19 IN COLUMN

Variability

- Variability: differences in speed of individual transistors
 - Nowadays, transistor dimensions measure just dozens of atoms!
 - If fab can't ensure uniformity of transistors, speeds will differ
 - Speed differences come from variations in V_{th}: low V_{th} → cycle time ↓ but power ↑ high V_{th} → cycle time ↑ but power ↓
- If unlucky and a logic path has lots of slow transistors
 - → CPU may miss clock cycle time if path is exercised
 - → CPU must be discarded, since it malfunctions
 - → Leads to low chip *yield*

Wafer Yield





- Yield is 85% (17 out of 20 tested dies or chips)
- Lower yield leads to higher production cost

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Variability

- Where did Variability push architecture?
- Product binning: Sell slower CPUs at a cheaper "bin"
 - And rate slower CPUs at a lower CPU frequency
 - Instead of discarding them as "malfunctioning"
- Multi-cores: Easy to disable one or two buggy cores
 - Compared to single core where subcomponents must be disabled
 - Used when one or two cores are extremely slow
- Limited pipelining: pipelining exacerbates variability
 - With long stages, many transistors so tend to even each other out
 - With short stages, few transistors so probable all are slow



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NA SAN		
V	TSBU	RGH

Model	# Cores	# Threads	Base	All Core	Turbo	Total L3	PL1 TDP
			Clock	Turbo	Boost	Cache	
i9-10900K	10	20	3.7	4.8	5.1	20	125
i9-10900KF	10	20	3.7	4.8	5.1	20	125
i9-10900	10	20	2.8	4.5	5.0	20	65
i9-10900F	10	20	2.8	4.5	5.0	20	65
i9-10900T	10	20	1.9	3.7	4.5	20	35
i7-10700K	8	16	3.8	4.7	5.0	16	125
i7-10700KF	8	16	3.8	4.7	5.0	16	125
i7-10700	8	16	2.9	4.6	7.7	16	65
i7-10700F	8	16	2.9	4.6	4.7	16	65
i7-10700T	8	16	2.0	3.7	4.4	16	35
i5-10600K	6	12	4.1	4.5	4.8	12	125
i5-10600K	6	12	4.1	4.5	4.8	12	125
i5-10600	6	12	3.3	4.4	4.8	12	65
i5-10600T	6	12	2.4	3.7	4.0	12	35
i5-10500	6	12	3.1	4.2	4.5	12	65
i5-10500T	6	12	2.3	3.5	3.8	12	35
i5-10400	6	12	2.9	4.0	4.3	12	65
i5-10400F	6	12	2.9	4.0	4.3	12	65
i5-10400T	6	12	2.0	3.2	3.6	12	35

Why the close to 4X difference?

Produced from one wafer

Source: https://www.techspot.com/article/2039-chip-binning/

^{*} TDP is calculated using the Base Clock frequency at a nominal supply voltage

Opportunities for Speed Improvement

- So Dennard Scaling is dead
 - Free CPU frequency gains are no longer there
- And we are walled in by technology constraints
 - Power wall
 - Memory wall
 - Variability
 - ...

Where do architects go look for performance?

Improving Execution Time



Execution time =
$$\frac{\text{instructions}}{\text{program}}$$
 X $\frac{\text{cycles}}{\text{instructions}}$ X $\frac{\text{seconds}}{\text{cycle}}$

- Improving $\frac{\text{seconds}}{\text{cycle}}$:
 - Pipelining can lead to higher frequencies (by having short stages separated by latches)
- Improving $\frac{\text{cycles}}{\text{instructions}}$:
 - Superscalars can execute multiple instructions per cycle
 - Multi-cores execute multi-instructions from multi-threads
- Improving instructions program :
 - GPUs are SIMD (Single Instruction Multiple Data) processors

What about Other Performance Goals?

- We talked a lot about execution speed
- But there are other performance goals such as:
 - Energy efficiency
 - Reliability
 - Security
 - ...
- In this class, we will mainly focus on speed
 - Not that other goals are not important
 - We will touch upon other goals when relevant
 - Performance will be used synonymously with speed



Textbook Chapters

Please review Chapter 1 of the textbook.